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(12) **United States Design Patent**
Liu et al.

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(54) **CPU HEAT SINK PACKAGING BOX**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl. 09-03**

(52) **U.S. Cl. D9/415**

(58) **Field of Classification Search** D9/415,
D9/414, 418, 430; 206/461, 462, 463, 464,
206/465, 471, 485, 486-488

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a CPU heat sink packaging box,
as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a CPU heat sink packaging box
showing our new design, in disassembled condition;

FIG. 2 is a top plan view thereof, in assembled condition;

FIG. 3 is a side elevational view thereof;

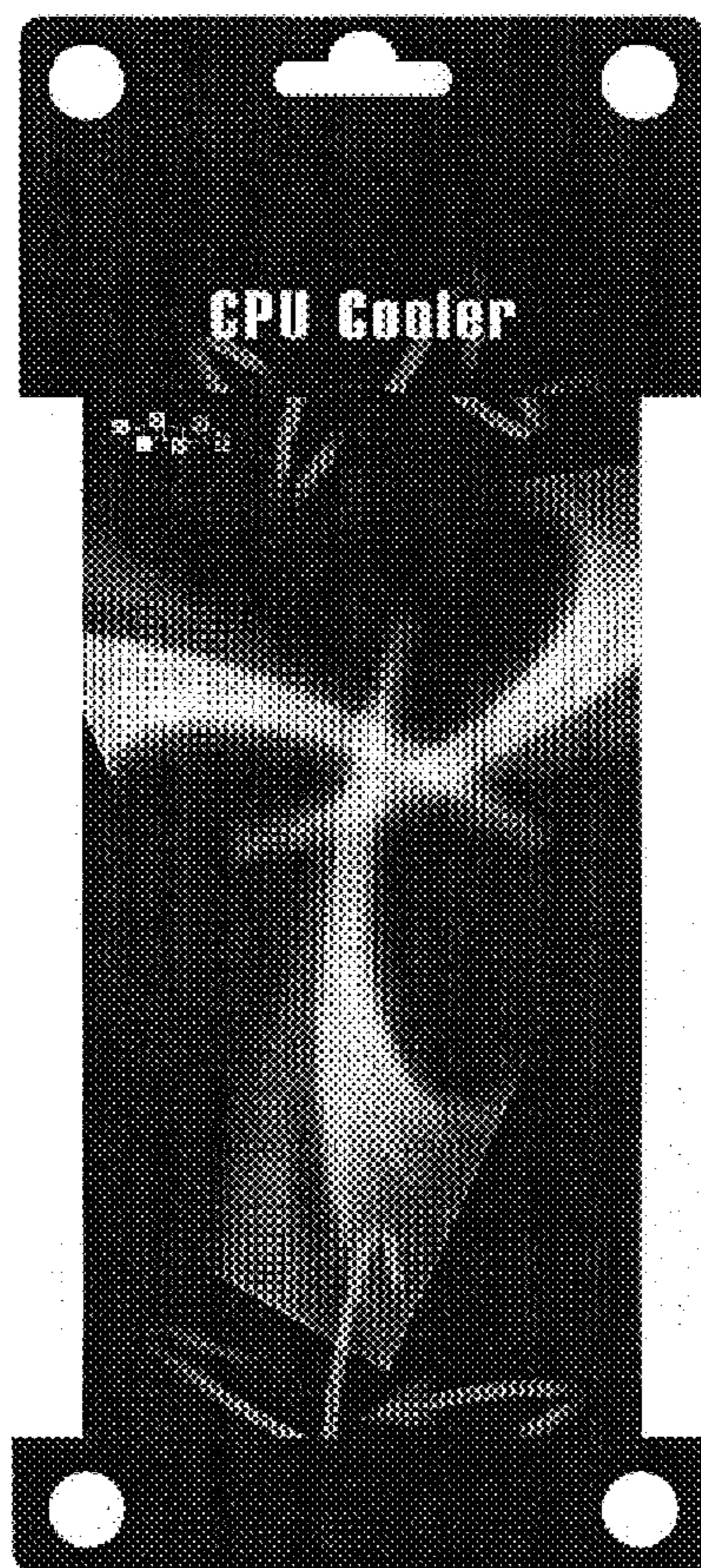
FIG. 4 is a side elevational view thereof from the side
opposite that shown in FIG. 3;

FIG. 5 is an end elevational view thereof; and,

FIG. 6 is an end elevational view thereof from the end
opposite that shown in FIG. 5.

The black shading in the drawing is intended to represent the
color black in the claimed design.

1 Claim, 4 Drawing Sheets



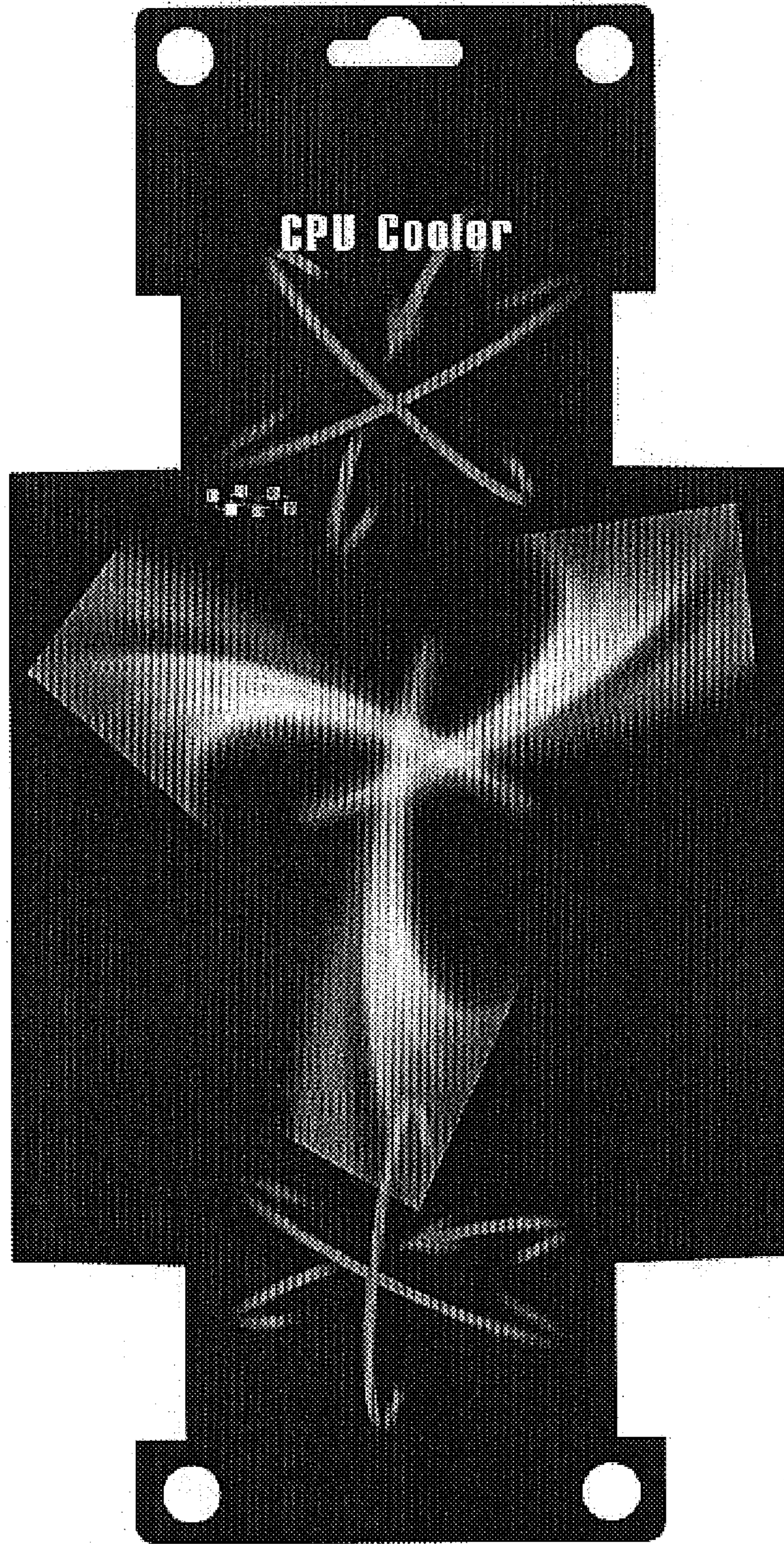


FIG. 1

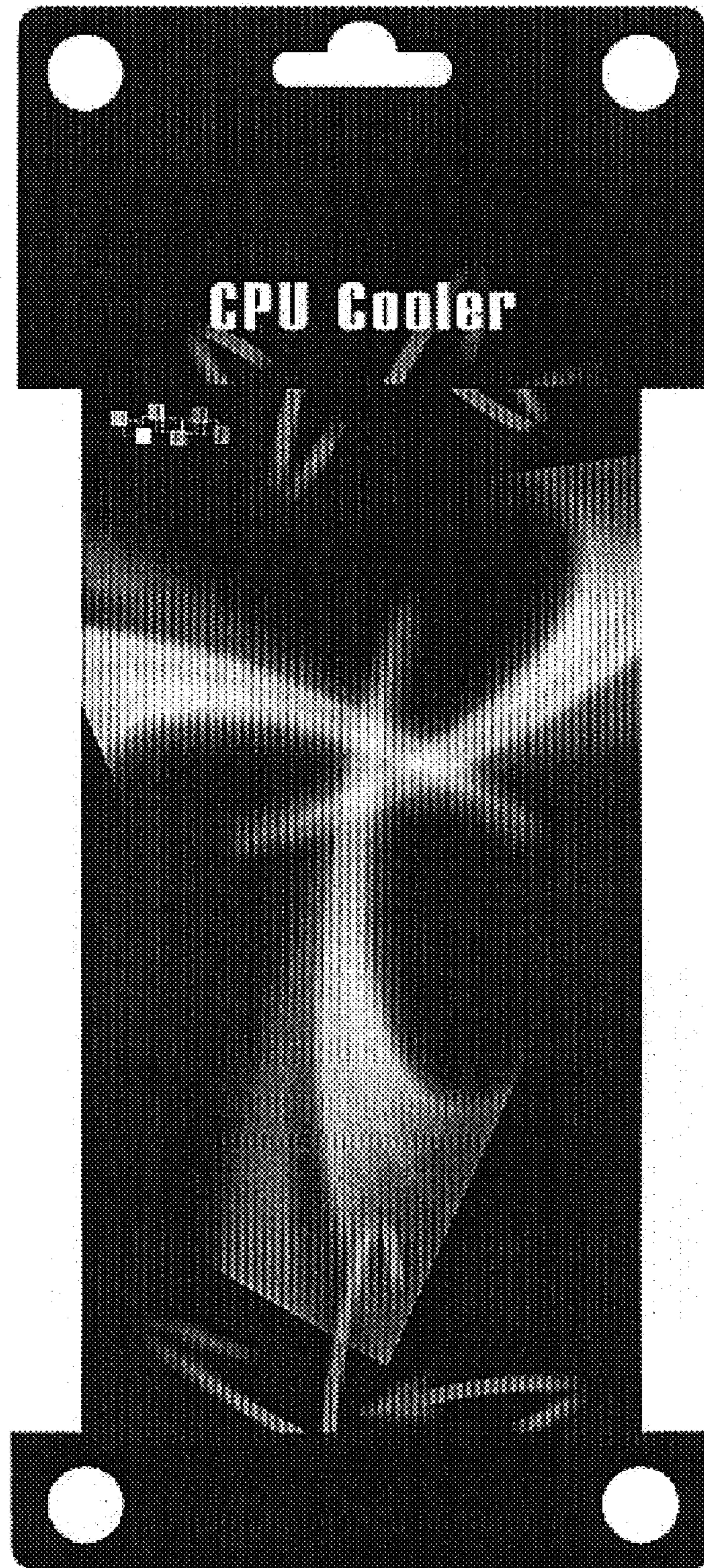


FIG. 2

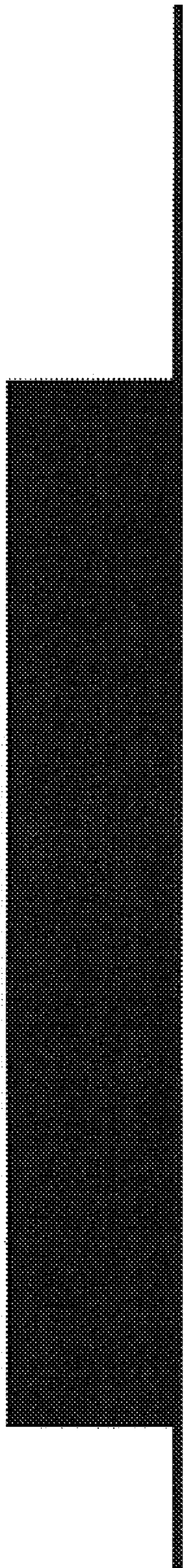


FIG. 3

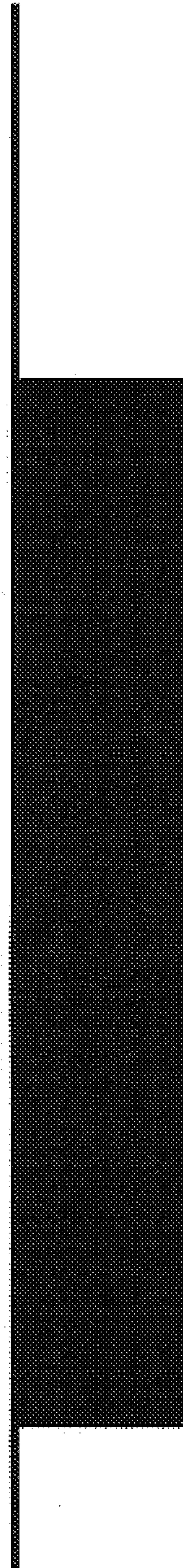


FIG. 4



FIG. 5



FIG. 6